1. A method comprising:

coupling a first and second surface of an electronic device; and

injecting an encapsulant between said first and second surfaces through one of said surfaces.

2. The method of claim 1 wherein injecting an encapsulant includes forming a hole through one of said surfaces and injecting encapsulant through said hole.

3. The method of claim 2 including forming a centrally located hole and forming a plurality of radially displaced holes arranged at a substantially uniform radius from said centrally located hole.

4. The method of claim 3 including injecting encapsulant through said centrally located hole until the encapsulant reaches said radially displaced holes and thereafter stopping the injection of encapsulant through said centrally located hole and injecting encapsulant through said radially displaced holes.

5. The method of claim 1 wherein injecting an encapsulant includes causing an encapsulant front to extend outwardly from the center of a region to be encapsulated between said first and second surfaces.

6. The method of claim 5 including injecting encapsulant through a central hole through one of said surfaces.

7. The method of claim 6 including terminating the injection of encapsulant through said central hole and injecting encapsulant through a plurality of holes substantially uniformly radially displaced with respect to said central hole.

8. The method of claim 7 including stopping the injection of said encapsulant through radially displaced holes and initiating the injection of encapsulant through a second set of holes radially displaced with respect to said radially displaced holes.

9. The method of claim 1 including forming an electronic display.

10. The method of claim 1 including injecting encapsulant into the region between a pair of spaced plates.

11. An electronic device comprising:
a first surface;

a second surface spaced from said first surface, said second surface including at least one encapsulation injection port extending through said surface; and

encapsulation between said first and second surfaces.

12. The device of claim 11 wherein said device is a display.

13. The device of claim 11 wherein one of said surfaces is a glass panel.

14. The device of claim 11 wherein said surfaces are surface mounted to one another.

15. The device of claim 11 wherein said device is an organic light emitting display device.

16. The device of claim 11 including a plurality of encapsulation injection ports extending through said first surface.

17. The device of claim 16 including a centrally located injection port, and a first array of substantially uniformly radially displaced injection ports positioned

radially outwardly of said centrally located injection port.

18. The device of claim 17 including a second array of substantially uniformly displaced injection ports positioned radially outwardly with respect to said first array.

19. A method comprising:

injecting encapsulant into an electronic device at a first location; and

when the encapsulant reaches a second location spaced from said first location, injecting encapsulant at a location proximate to said second location.

20. The method of claim 19 including coupling a first and second surface of an electronic device and injecting encapsulant between said first and second surfaces.

21. The method of claim 20 including forming a centrally located hole and forming a plurality of radially displaced holes arranged at a substantially uniform radius from said centrally located hole.

22. The method of claim 21 including injecting encapsulant through said centrally located hole until the encapsulant reaches said radially displaced holes and thereafter stopping the injection of encapsulant through said centrally located hole and injecting encapsulant through said radially displaced holes.

23. The method of claim 19 including forming an electronic display.

24. The method of claim 19 including injecting encapsulant into a region between a pair of spaced plates.

25. The method of claim 24 including injecting encapsulant through one of said plates.